

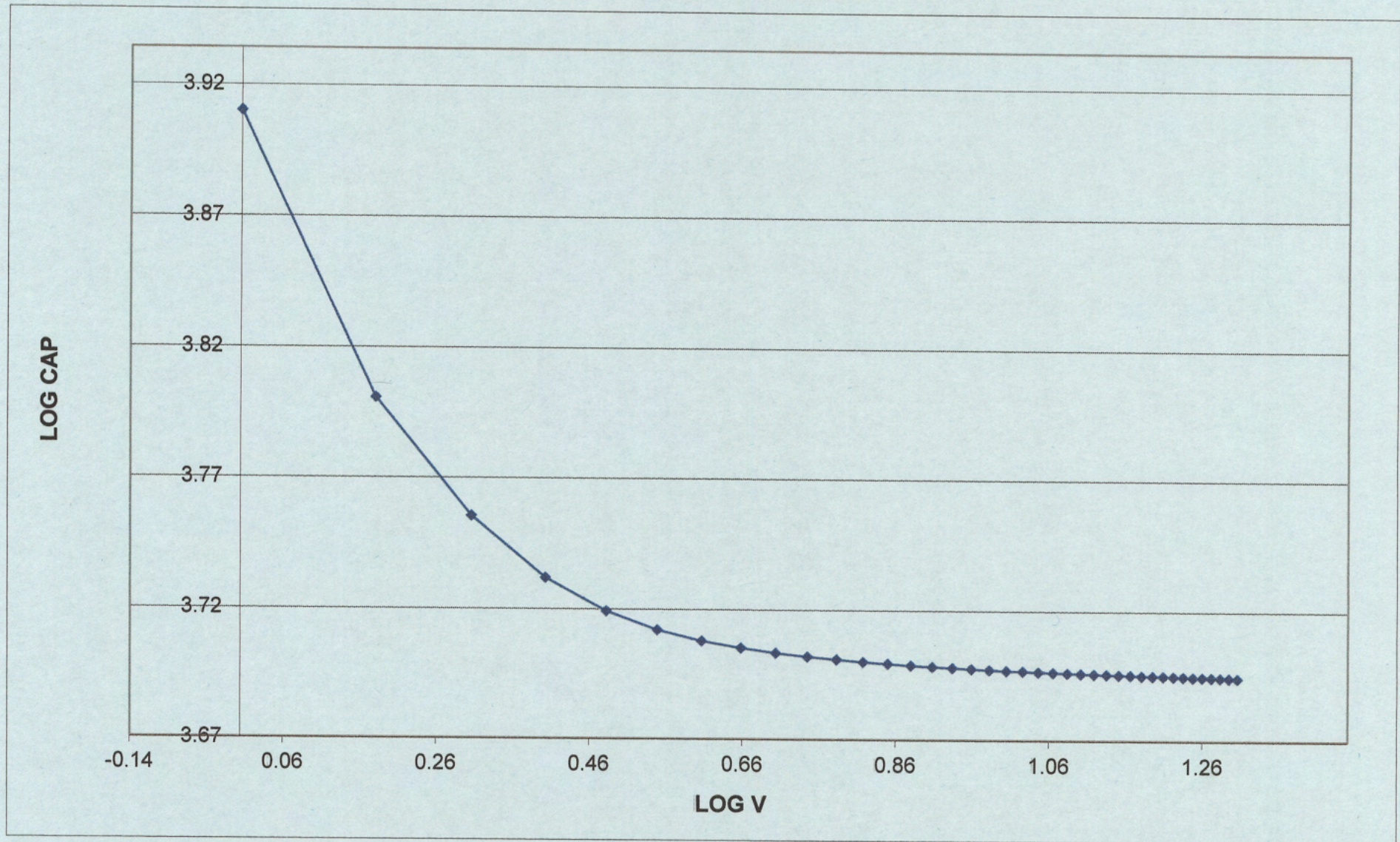
Depletion Plot

S5-65

Wafer No.: **3560-4**

Thickness: **72** um

Depletion: **7.2** Volts





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PACKING CHECK LIST

[To be completed for ALL shipments leaving MSL – in-house document only]

CUSTOMER	CSIC
PURCHASE ORDER NO	12m/001/22

	CHECK LIST	DATE	SIGNATURE
1	Yellow Sheet Provided (ensure latest revision).	24-10-22	DD
2	Assembly Batch Traveller Provided	24-10-22	DD
3	Detector/Item Details [Specify Quantity/Design/Serial (or ID) No/Thickness. Ensure that the information on this packing check list matches the packed item(s) and test data.] <i>Continue overleaf, if necessary.</i> 55-65 (D/S) 3560-4 / 72um	24-10-22	DD
4	Test Data Documentation Provided/Checked [against the above details/packed detector(s)]/Uploaded to DropBox.	24-10-22	DD
5	Vibration Test Data Provided (if required). [“Astrium Test Certificate”: this applies to flight model detectors only.]	—	
6	Mating Connectors Provided (if specified on the eYS).	24-10-22	DD
7	Assembly Drawing(s) Provided (give details). [Check that the correct drawing(s) has (have) been provided against the details specified in the relevant Job Pack.] A-5518	24-10-22	DD
8	Customer Packing List [Form No 52] Provided (for inclusion in box/supplied to customer).	24-10-22	DD
9	Product(s) Tightly Packed in Foam and Detector Handling Instructions Provided.	24-10-22	DD
10	Yield/Failure Analysis Form (Form 10) to QA Dept.	24-10-22	DD
11	Packing List Completed by (Assembly Team).	24-10-22	DD
12	Packing List signed off by (2 nd member of relevant Assembly Team or Project Manager).	24.10.22	DL
13	Certificate of conformity required? YES (NO)		

Office staff to ensure that the box contains all relevant paperwork, including any special documents, such as a Certificate of Conformity (check against customer PO for details).

Micron Semiconductor Ltd.

Assembly Batch Traveller

Customer: <i>CSIC</i>	Customer Purchase Order Number: <i>LEM/001/22</i>
Device type: <i>SS</i>	
Wafer Type: <i>4" / 65</i>	circle process type front 2 7 <u>9</u> 9.5 M G <u>P</u> T D other back 2 <u>7</u> 9 9.5 M G <u>P</u> T D other
Wafer Numbers:	
<i>3560-6/70</i> <i>CRACK</i> <i>3560-1/71</i> <i>3560-4/72</i>	

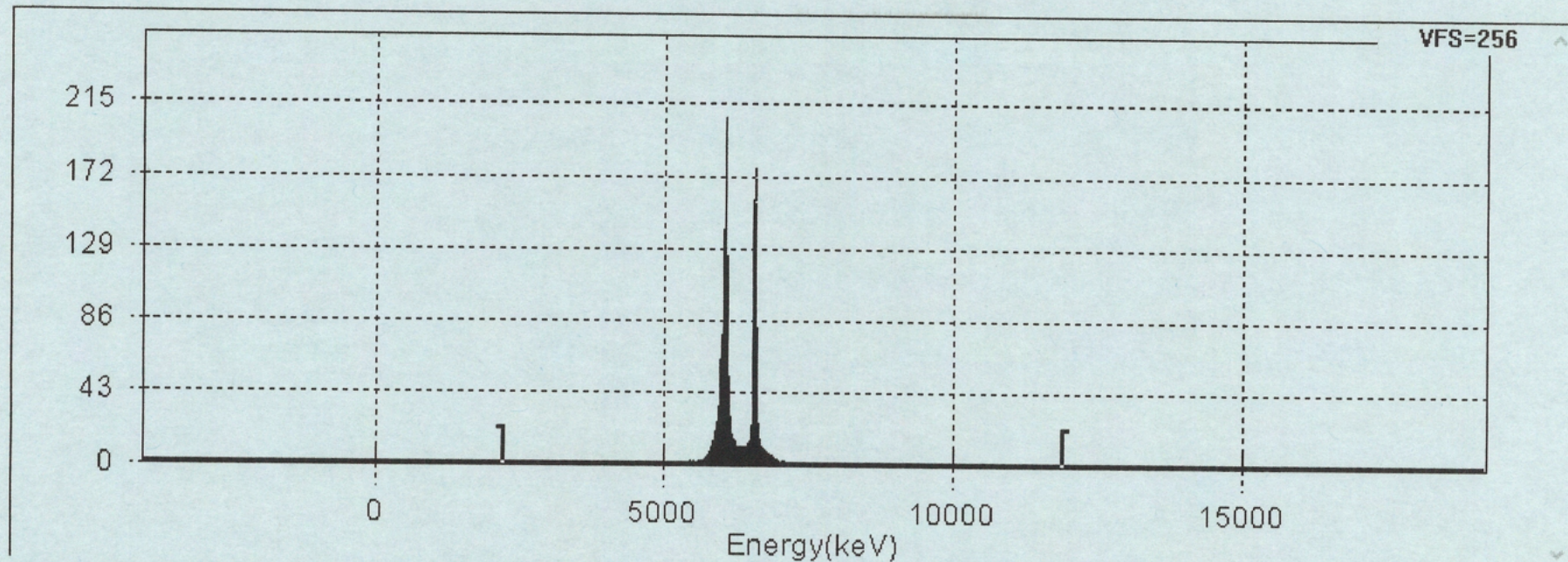
Process	Date Completed	Comment	Operator
Saw blank film frame ensuring nitto film scored	<i>3.10.22</i>	<i>-6 MAKE</i>	<i>JD</i>
Wafer sawing/laser	<i>//</i>	WI 898	<i>JD</i>
Die release	<i>//</i>	WI 874	<i>JD</i>
Wafer cleaning	<i>//</i>	WI 855, 891, 891a	<i>JD</i>
Die oven dry	<i>//</i>		<i>JD</i>
Visual inspection	<i>//</i>		<i>JD</i>

INITIAL RESULTS

Leakage current			
Forward Voltage @10mA			
Breakdown voltage			

Visual inspection	<i>11-10-22</i>	<i>3560-1 small scratch on front</i>	<i>JR</i>
Die attachment: Resin type	<i>11/10/22</i>	Resin batch no. <i>Aug 11</i> <i>SCR-259068 93974</i>	<i>JR</i>
Wire bonding: Destructive wire pull test value	<i>14-10-22</i>	Wire type batch no. <i>LOT NO: 5080618</i>	<i>AF</i>
Final testing	<i>17/10/22</i>	<i>#4 good dev. 4</i>	<i>JR</i>
Alpha Resolution Test	<i>21/10/22</i>	<i>#4 good < 75 kW</i>	<i>NR</i>
Visual inspection	<i>21-10-22</i>	<i>surface dust</i> <i>All wirebonds in sack.</i>	<i>JD</i>
Packing Approval: Project Manager/Assembly Manager			
Acceptance to specification and release for sale (Project / Quality Manager only)			<i>Paul Lehn</i> <i>21/10/22</i>

VFS=256 ^

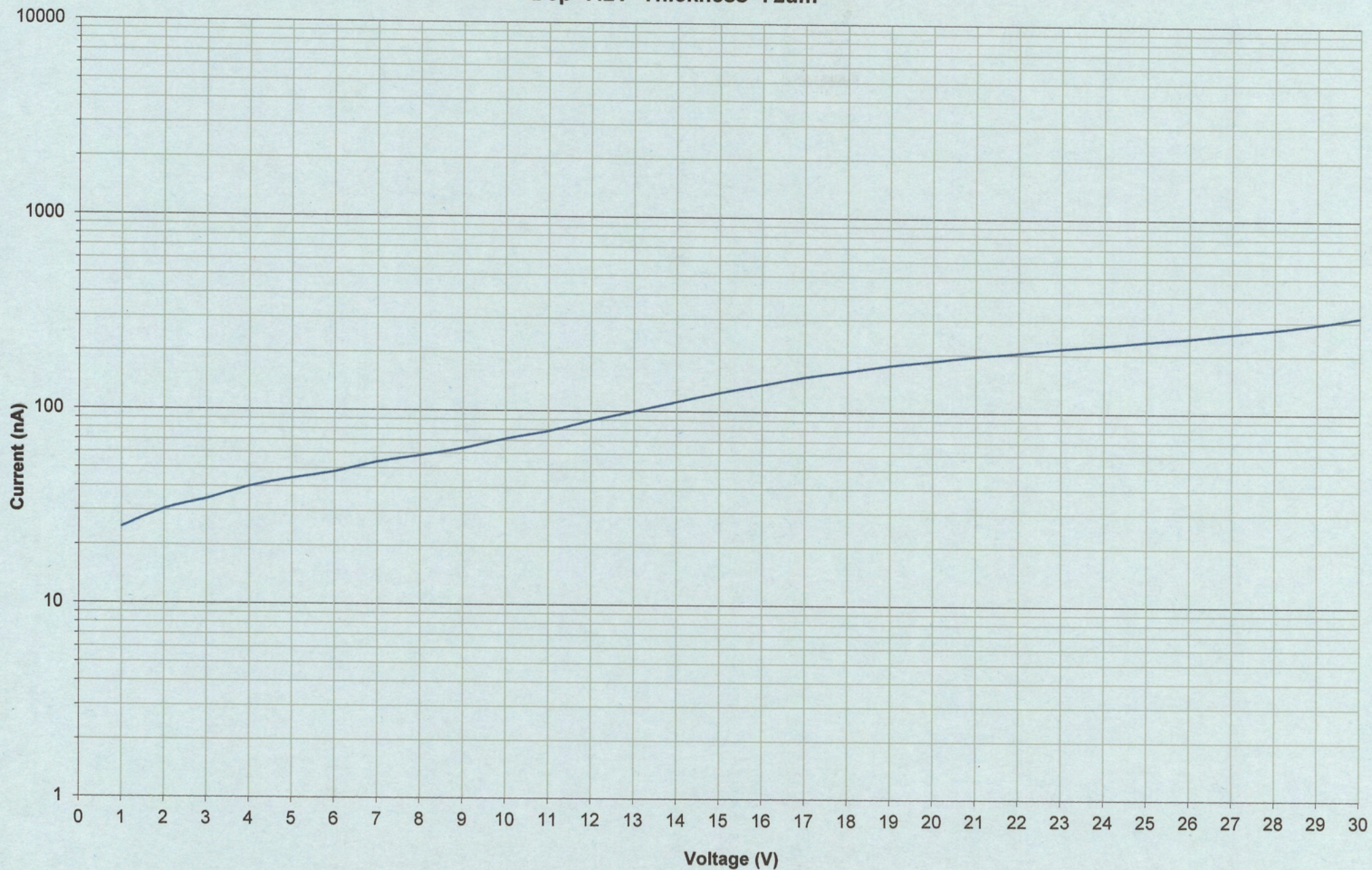


3560-4 DESIGN S5-65 VBIAS- 10 VOLTS IR- 93 nA TEMP-22.1DC T= 72 MICRONS DATE:20/10/2022
LEAKAGE TOTAL FOR ALL STRIPS BIASED

DETECTOR LINE - 63.5 Kev (NN+)	DETECTOR LINE- 65.0 Kev
SYSTEM- 45.0 Kev	SYSTEM- 44.8 Kev
CALCULATED- 44.8 Kev	CALCULATED- 47.1 Kev

RESOLUTION OF OHMIC JUNCTION STRIP 4

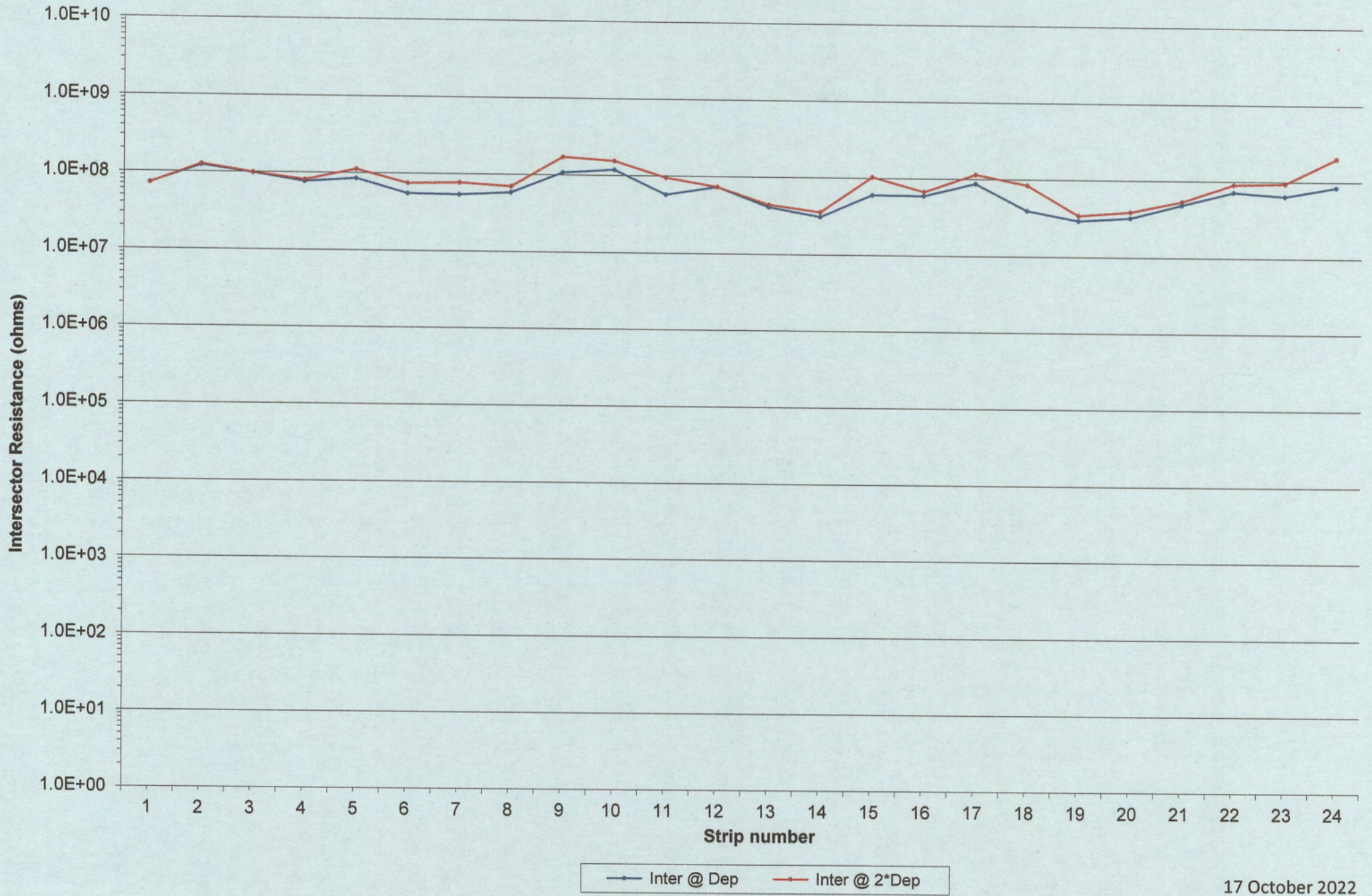
S5-65 D/S
3560-4 TOTAL DETECTOR IV
Dep=7.2V Thickness=72um



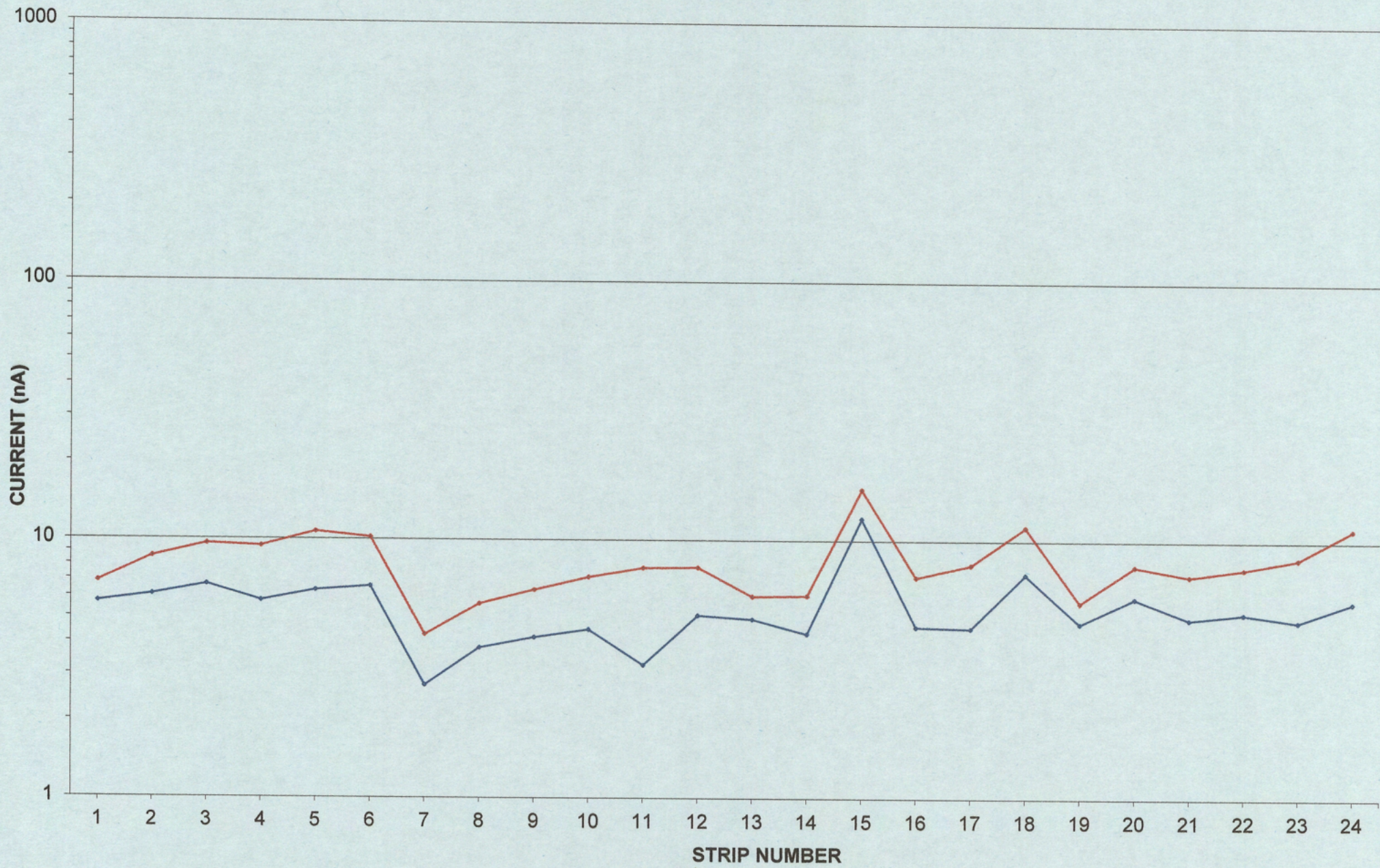
— All sectors combined

17 October 2022

S5_65 D/S
3560-4 Junction side Dep=7.2V

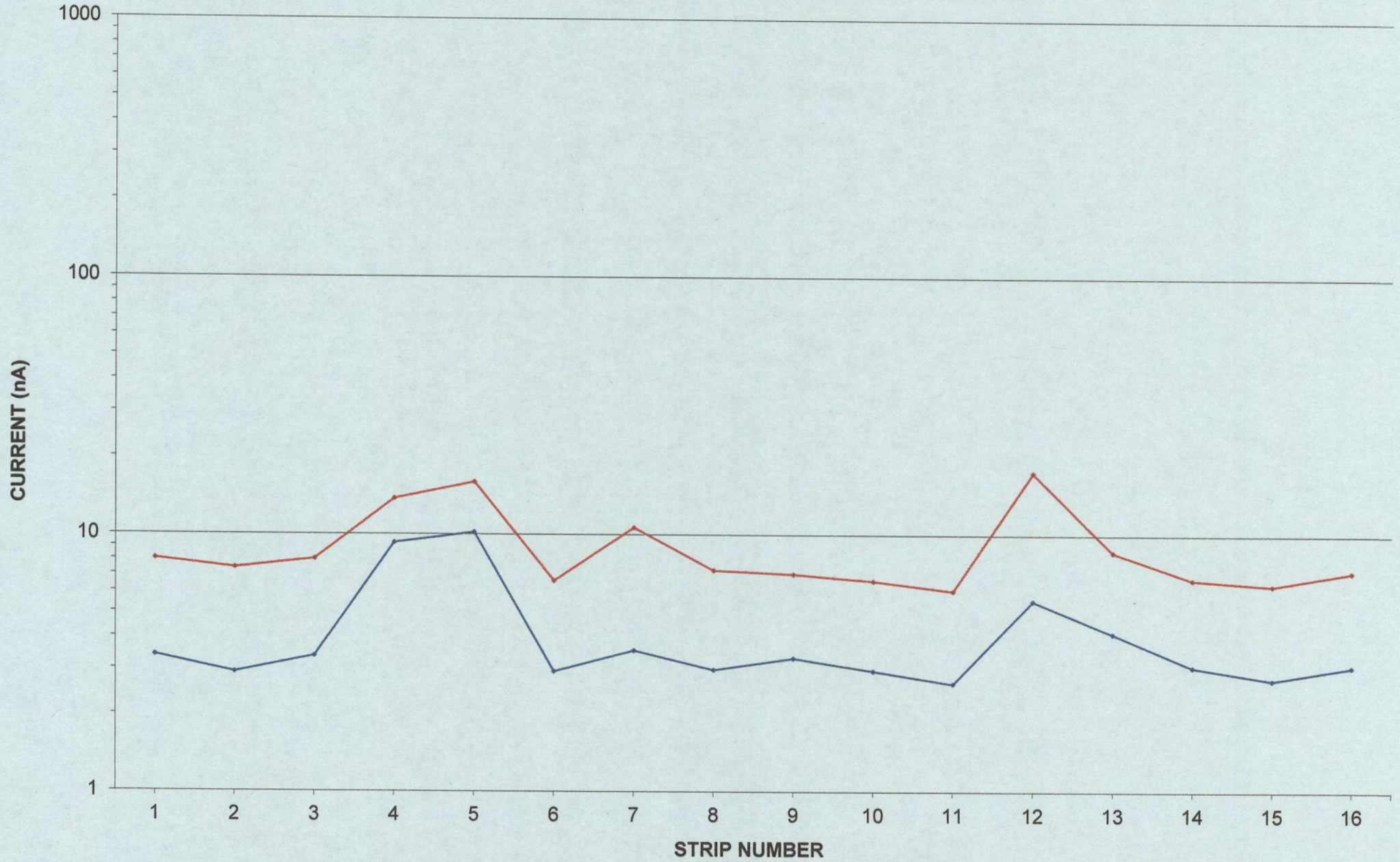


S5_65 D/S
3560-4 Junction side Dep=7.2V



—•— current @ Dep —•— current @ 2*Dep

S5_65 D/S
3560-4 Ohmic side Dep=7.2V



—◆— current @ Dep —◆— current @ 2*Dep

17 October 2022

S5_65 D/S
3560-4 Ohmic side Dep=7.2V

